

CLAIMS

What is claimed is:

- 1 1. A method for connecting an electrical device to an electrical
2 component, the electrical device comprising at least one ledge that comprises a
3 plurality of contact terminals, the method comprising:
4 connecting a conductor member to one of the contact terminals provided on
5 the ledge of the electrical device;
6 extending the conductor member outwardly along the ledge;
7 extending the conductor member down from the ledge toward the electrical
8 component; and
9 connecting the conductor member to a contact of the electrical component.
- 1 2. The method of claim 1, wherein each conductor member comprises a
2 bond wire.
- 1 3. The method of claim 2, wherein the bond wire is formed with a wire
2 bonding technique.
- 1 4. The method of claim 1, wherein the electrical device is an ARS device.
- 1 5. The method of claim 1, wherein the electrical component is a PCB.

1 6. A method for connecting an electrical device to an electrical
2 component, the electrical device comprising at least one ledge that comprises a
3 plurality of contact terminals, the method comprising:
4 orienting the electrical device such that the ledge faces the electrical
5 component;
6 aligning the portion of the electrical device facing the electrical component
7 with a cavity formed in the electrical component; and
8 inserting the portion of the electrical device facing the electrical component
9 into the cavity so that at least one of the contact terminals makes electrical contact
10 with a contact of the electrical device.

1 7. The method of claim 6, wherein the electrical device is inverted when
2 its ledge faces the electrical component.

1 8. The method of claim 6, wherein the portion of the electrical device
2 facing the electrical component comprises a top layer of the electrical device.

1 9. The method of claim 8, wherein the cavity is sized and configured to
2 receive the entire top layer.

1 10. The method of claim 6, wherein the electrical device is affixed in place
2 with a solder material.

1 11. The method of claim 6, wherein the electrical device is affixed in place
2 with an electrically conductive adhesive material.

1 12. The method of claim 6, wherein the electrical device is an ARS device.

1 13. The method of claim 6, wherein the electrical component is a PCB.

1 14. An assembly, comprising:
2 an electrical component having a plurality of contacts formed thereon; and
3 an electrical device having at least one ledge that includes a plurality of
4 contact terminals provided thereon at least one of the contact terminals being
5 electrically connected to at least one of the contacts formed on the electrical
6 component.

1 15. The assembly of claim 14, further comprising at least one conductor
2 member that electrically connects the at least one contact terminal of the electrical
3 device to the at least one contact of the electrical component.

1 16. The assembly of claim 15, wherein the at least one conductor member
2 comprises a bond wire.

1 17. The assembly of claim 14, wherein the electrical component comprises
2 a cavity that is sized and configured to receive a portion of the electrical device such
3 that the contact terminals are arranged in direct opposition to the contacts of the
4 electrical component when the electrical device is disposed within the cavity.

1 18. The assembly of claim 17, wherein the at least one contact terminal of
2 the electrical device and the at least one contact of the electrical component are
3 soldered together.

1 19. The assembly of claim 17, wherein the at least one contact terminal of
2 the electrical device and the at least one contact of the electrical component are
3 adhered to each other with electrically conductive adhesive.

1 20. The assembly of claim 14, wherein the electrical device is an ARS
2 device.

1 21. The assembly of claim 14, wherein the electrical component is a PCB.